

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the above-referenced application.

Listing of Claims:

1. (Original) A method of shielding a circuit device, comprising:

- (a) providing a circuit board on which an electronic component has mounted and which has a ground connection portion;
- (b) inserting an entire portion of said circuit board into a shield pack having a sack shape, said shield pack having an insulating layer as an innermost layer and an electric conductive layer as an outermost layer; and
- (c) contacting said insulating layer of said shield pack with said electronic component and said circuit board,

wherein said ground connection portion of said circuit board is connected to said electric conductive layer of said shield pack.

2. (Original) The shielding method of a circuit device according to claim 1, wherein said (c) contacting step comprises:

- (d) reducing an internal capacity of said shield pack.

3. (Currently amended) The shielding method of a circuit device according to claim 2, wherein said circuit board [[is]] further comprises a ground connection terminal connected to said ground connection portion, and

said ground connection terminal breaks through said shield pack to be connected with said electric conductive layer during said (c) contacting step.

4. (Currently amended) The shielding method of a circuit device according to claim 3, wherein said ground connection terminal comprises:

a tip portion having a conical shape; and
a base portion connected to said tip portion, [[and]] wherein said base portion has a sectional area which is smaller than a bottom plane of said cone such that said base portion does not project from the bottom plane of said cone.

5. (Original) The shielding method of a circuit device according to claim 4, wherein said base portion of said ground connection terminal has a height which is substantially equal to a thickness of said shield pack, and

when said tip portion breaks through said shield pack, the bottom plane of said cone is connected to said electric conductive layer.

6. (Original) The shielding method of a circuit device according to claim 2, further comprising:

connecting said ground connection portion and said electric conductive layer by passing an electric conductive connection component through said ground connection portion between said shield pack and said circuit board, after said insulating layer of said shield pack is fit with said electronic component and said circuit board.

7. (Original) The shielding method of a circuit device according to claim 6, wherein said circuit

board has a through-hole formed in said ground connection portion,
said through-hole is filled with an electric conductor connected to said ground
connection portion, and

said connection component passes through said through-hole to connect said
ground connection portion with said electric conductive layer.

8. (Currently amended) The shielding method of a circuit device according to claim 6 [[or 7]],

wherein said connection component is used to fix said circuit board contained within said
shield pack to a housing, and

said housing has an electric conductive portion connected to said electric
conductive layer.

9. (Currently amended) The shielding method of a circuit device according to claim 3 any of

claims 3 to 5, wherein said (d) reducing step comprises:

vacuum-sucking air contained in said shield pack such that said insulating layer of
said shield pack contacts said electronic component and said circuit board.

10. (Currently amended) The shielding method of a circuit device according to claim 3 any of
~~claims 3 to 5~~, wherein an adhesive agent is coated on at least a portion of said circuit
board and at least a portion of an outer surface of said electronic component, and
said (d) reducing step comprises:

vacuum-sucking air contained in said shield pack such that said insulating layer of
said shield pack contacts said electronic component and said circuit board.

11. (Currently amended) The shielding method of a circuit device according to claim 3 any of
~~claims 3 to 5~~, wherein said shield pack is made of thermal shrinkage material, and
said (d) reducing step comprises:

heating said shield pack such that said insulating layer of said shield pack contacts
said electronic component and said circuit board.

12. (Currently amended) The shielding method of a circuit device according to claim 3 any of
~~claims 3 to 5~~, wherein an adhesive agent is coated on at least a portion of said circuit
board and at least a portion of an outer surface of said electronic component,
said shield pack is made of thermal shrinkage material, and
said (d) reducing step comprises:

heating said shield pack such that said insulating layer of said shield pack contacts
said electronic component and said circuit board.

13. (Original) An electromagnetically shielded circuit device comprising:

a circuit board on which an electronic component has been mounted and which has a ground connection portion;

a sack-shaped shield pack which covers an entire portion of said circuit board, said shield pack having an insulating layer as an innermost layer and an electric conductive layer as an outermost layer; and

an electric conductive connection component which passes through said shield pack to said circuit board to connect said ground connection portion to said electric conductor layer of said shield pack.

14. (Original) The electromagnetically shielded circuit device according to claim 13, wherein said connection component is a ground connection terminal which is previously fixedly provided to said ground connection portion of said circuit board.

15. (Original) The electromagnetically shielded circuit device according to claim 14, wherein said ground connection terminal has a tip portion having a conical shape and a base portion connected to said tip portion, and

said base portion has a sectional area which is smaller than a bottom plane of said cone such that said base portion does not project from the bottom plane of said cone.

16. (Original) The electromagnetically shielded circuit device according to claim 15, wherein
said base portion of said ground connection terminal has a height which is substantially
equal to a thickness of said shield pack, and
the bottom plane of said cone is connected to said electric conductive layer under
in a state that said tip portion breaks through said shield pack.

17. (Original) The electromagnetically shielded circuit device according to claim 13, wherein
said circuit board has a through-hole formed in said ground connection portion,
said through-hole is filled with an electric conductor connected to said ground
connection portion, and
said connection component passes through said through-hole to connect said
ground connection portion with said electric conductive layer.

18. (Currently amended) The electromagnetically shielded circuit device according to claim 13
[[or 17]], wherein said connection component is a vis, and is used to fix said circuit board
contained within said shield pack to a housing, and
said housing has an electric conductive portion connected to said electric
conductive layer.